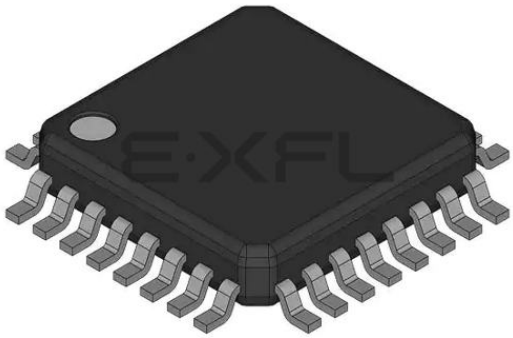

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	I²C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	32
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at91sam7s128c-au-999

3. Signal Description

Table 3-1. Signal Description List

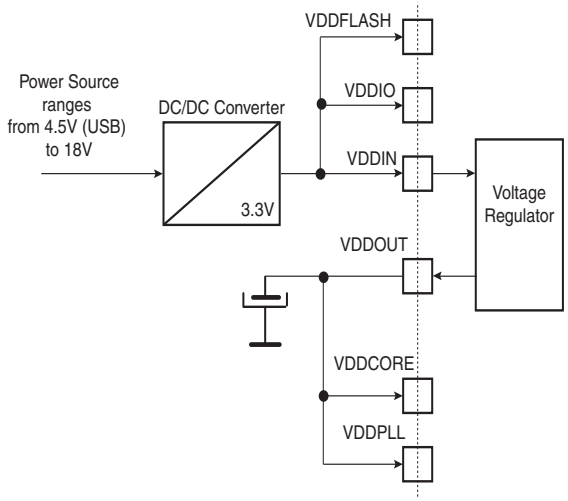
VDDIN	Voltage and ADC Regulator Power Supply Input	Power		3.0 to 3.6V
VDDOUT	Voltage Regulator Output	Power		1.85V nominal
VDDFLASH	Flash Power Supply	Power		3.0V to 3.6V
VDDIO	I/O Lines Power Supply	Power		3.0V to 3.6V or 1.65V to 1.95V
VDDCORE	Core Power Supply	Power		1.65V to 1.95V
VDDPLL	PLL	Power		1.65V to 1.95V
GND	Ground	Ground		
XIN	Main Oscillator Input	Input		
XOUT	Main Oscillator Output	Output		
PLLRC	PLL Filter	Input		
PCK0 - PCK2	Programmable Clock Output	Output		
TCK	Test Clock	Input		No pull-up resistor
TDI	Test Data In	Input		No pull-up resistor
TDO	Test Data Out	Output		
TMS	Test Mode Select	Input		No pull-up resistor
JTAGSEL	JTAG Selection	Input		Pull-down resistor(1)
ERASE	Flash and NVM Configuration Bits Erase Command	Input	High	Pull-down resistor(1)
NRST	Microcontroller Reset	I/O	Low	Open-drain with pull-Up resistor
TST	Test Mode Select	Input	High	Pull-down resistor(1)
DRXD	Debug Receive Data	Input		
DTXD	Debug Transmit Data	Output		
IRQ0 - IRQ1	External Interrupt Inputs	Input		IRQ1 not present on SAM7S32/16
FIQ	Fast Interrupt Input	Input		
PA0 - PA31	Parallel IO Controller A	I/O		Pulled-up input at reset PA0 - PA20 only on SAM7S32/16

Table 3-1. Signal Description List (Continued)

TWD	Two-wire Serial Data	I/O		
TWCK	Two-wire Serial Clock	I/O		
AD0-AD3	Analog Inputs	Analog		Digital pulled-up inputs at reset
AD4-AD7	Analog Inputs	Analog		Analog Inputs
ADTRG	ADC Trigger	Input		
ADVREF	ADC Reference	Analog		
PGMEN0-PGMEN2	Programming Enabling	Input		
PGMM0-PGMM3	Programming Mode	Input		
PGMD0-PGMD15	Programming Data	I/O		PGMD0-PGMD7 only on SAM7S32/16
PGMRDY	Programming Ready	Output	High	
PGMNVALID	Data Direction	Output	Low	
PGMNOE	Programming Read	Input	Low	
PGMCK	Programming Clock	Input		
PGMNCMD	Programming Command	Input	Low	

Note: 1. Refer to Section 6. “I/O Lines Considerations” on page 14.

Figure 5-1. 3.3V System Single Power Supply Schematic



6. I/O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are schmitt trigger inputs. TMS and TCK are 5-V tolerant, TDI is not. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

6.2 Test Pin

The TST pin is used for manufacturing test, fast programming mode or SAM-BA Boot Recovery of the SAM7S Series when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied to low.

To enter SAM-BA Boot Recovery, the TST pin and the PA0, PA1 and PA2 pins should be tied high for at least 10 seconds. Then a power cycle of the board is mandatory.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the pin NRST as system user reset, and the use of the signal NRST to reset all the components of the system.

The NRST pin integrates a permanent pull-up resistor to VDDIO.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

6.5 PIO Controller A Lines

- All the I/O lines PA0 to PA31on SAM7S512/256/128/64/321 (PA0 to PA20 on SAM7S32) are 5V-tolerant and all integrate a programmable pull-up resistor.
- All the I/O lines PA0 to PA31 on SAM7S161 (PA0 to PA20 on SAM7S16) are **not** 5V-tolerant and all integrate a programmable pull-up resistor.

Programming of this pull-up resistor is performed independently for each I/O line through the PIO controllers.

5V-tolerant means that the I/O lines can drive voltage level according to VDDIO, but can be driven with a voltage of up to 5.5V. However, driving an I/O line with a voltage over VDDIO while the programmable pull-up resistor is enabled will create a current path through the pull-up resistor from the I/O line to VDDIO. Care should be taken, in particular at reset, as all the I/O lines default to input with the pull-up resistor enabled at reset.

6.6 I/O Line Drive Levels

The PIO lines PA0 to PA3 are high-drive current capable. Each of these I/O lines can drive up to 16 mA permanently.

The remaining I/O lines can draw only 8 mA.

However, the total current drawn by all the I/O lines cannot exceed 150 mA (100 mA for SAM7S32/16).

8. Memories

8.1 SAM7S512

- 512 Kbytes of Flash Memory, dual plane
  - 2 contiguous banks of 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 32 lock bits, protecting 32 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 64 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.2 SAM7S256

- 256 Kbytes of Flash Memory, single plane
  - 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 16 lock bits, protecting 16 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 64 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.3 SAM7S128

- 128 Kbytes of Flash Memory, single plane
  - 512 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 32 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.4 SAM7S64

- 64 Kbytes of Flash Memory, single plane
  - 512 pages of 128 bytes

- Fast access time, 30 MHz single-cycle access in Worst Case conditions
- Page programming time: 6 ms, including page auto-erase
- Page programming without auto-erase: 3 ms
- Full chip erase time: 15 ms
- 10,000 write cycles, 10-year data retention capability
- 16 lock bits, protecting 16 sectors of 32 pages
- Protection Mode to secure contents of the Flash

- 16 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.5 SAM7S321/32

- 32 Kbytes of Flash Memory, single plane
  - 256 pages of 128 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 32 pages
  - Protection Mode to secure contents of the Flash
- 8 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.6 SAM7S161/16

- 16 Kbytes of Flash Memory, single plane
  - 256 pages of 64 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 32 pages
  - Protection Mode to secure contents of the Flash
- 4 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.7 Memory Mapping

8.7.1 Internal SRAM

- The SAM7S512 embeds a high-speed 64-Kbyte SRAM bank.
- The SAM7S256 embeds a high-speed 64-Kbyte SRAM bank.
- The SAM7S128 embeds a high-speed 32-Kbyte SRAM bank.
- The SAM7S64 embeds a high-speed 16-Kbyte SRAM bank.
- The SAM7S321 embeds a high-speed 8-Kbyte SRAM bank.
- The SAM7S32 embeds a high-speed 8-Kbyte SRAM bank.
- The SAM7S161 embeds a high-speed 4-Kbyte SRAM bank.
- The SAM7S16 embeds a high-speed 4-Kbyte SRAM bank

After reset and until the Remap Command is performed, the SRAM is only accessible at address 0x0020 0000. After Remap, the SRAM also becomes available at address 0x0.

8.7.2 Internal ROM

The SAM7S Series embeds an Internal ROM. The ROM contains the FFPI and the SAM-BA program.

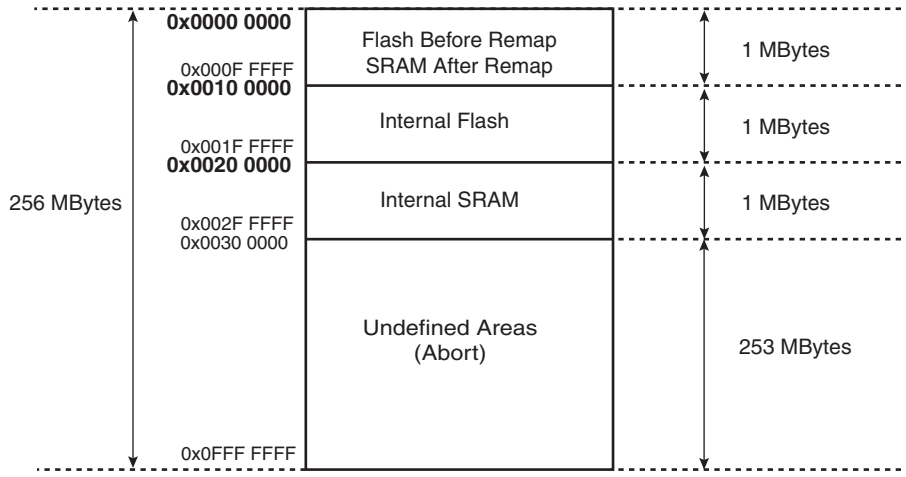
The internal ROM is not mapped by default.

8.7.3 Internal Flash

- The SAM7S512 features two contiguous banks (dual plane) of 256 Kbytes of Flash.
- The SAM7S256 features one bank (single plane) of 256 Kbytes of Flash.
- The SAM7S128 features one bank (single plane) of 128 Kbytes of Flash.
- The SAM7S64 features one bank (single plane) of 64 Kbytes of Flash.
- The SAM7S321/32 features one bank (single plane) of 32 Kbytes of Flash.
- The SAM7S161/16 features one bank (single plane) of 16 Kbytes of Flash.

At any time, the Flash is mapped to address 0x0010 0000. It is also accessible at address 0x0 after the reset and before the Remap Command.

Figure 8-2. Internal Memory Mapping



8.8 Embedded Flash

8.8.1 Flash Overview

- The Flash of the SAM7S512 is organized in two banks (dual plane) of 1024 pages of 256 bytes. The 524,288 bytes are organized in 32-bit words.
- The Flash of the SAM7S256 is organized in 1024 pages (single plane) of 256 bytes. The 262,144 bytes are organized in 32-bit words.
- The Flash of the SAM7S128 is organized in 512 pages (single plane) of 256 bytes. The 131,072 bytes are organized in 32-bit words.
- The Flash of the SAM7S64 is organized in 512 pages (single plane) of 128 bytes. The 65,536 bytes are organized in 32-bit words.
- The Flash of the SAM7S321/32 is organized in 256 pages (single plane) of 128 bytes. The 32,768 bytes are organized in 32-bit words.
- The Flash of the SAM7S161/16 is organized in 256 pages (single plane) of 64 bytes. The 16,384 bytes are organized in 32-bit words.
- The Flash of the SAM7S512/256/128 contains a 256-byte write buffer, accessible through a 32-bit interface.
- The Flash of the SAM7S64/321/32/161/16 contains a 128-byte write buffer, accessible through a 32-bit interface.

The Flash benefits from the integration of a power reset cell and from the brownout detector. This prevents code corruption during power supply changes, even in the worst conditions.

When Flash is not used (read or write access), it is automatically placed into standby mode.

8.8.2 Embedded Flash Controller

The Embedded Flash Controller (EFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped within the Memory Controller on the APB. The User Interface allows:

- programming of the access parameters of the Flash (number of wait states, timings, etc.)
- starting commands such as full erase, page erase, page program, NVM bit set, NVM bit clear, etc.
- getting the end status of the last command
- getting error status
- programming interrupts on the end of the last commands or on errors

The Embedded Flash Controller also provides a dual 32-bit prefetch buffer that optimizes 16-bit access to the Flash. This is particularly efficient when the processor is running in Thumb mode.

Two EFCs are embedded in the SAM7S512 to control each bank of 256 Kbytes. Dual plane organization allows concurrent Read and Program. Read from one memory plane may be performed even while program or erase functions are being executed in the other memory plane.

One EFC is embedded in the SAM7S256/128/64/32/321/161/16 to control the single plane 256/128/64/32/16 Kbytes.

8.8.3 Lock Regions

8.8.3.1 SAM7S512

Two Embedded Flash Controllers each manage 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S512 contains 32 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC_FMR register.

The 16 NVM bits (or 32 NVM bits) are software programmable through the corresponding EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.8.3.2 SAM7S256

The Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S256 contains 16 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC_FMR register.

The 16 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.8.3.3 SAM7S128

The Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S128 contains 8 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC_FMR register.

The 8 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.8.3.4 SAM7S64

The Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S64 contains 16 lock regions and each lock region contains 32 pages of 128 bytes. Each lock region has a size of 4 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC_FMR register.

The 16 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.8.3.5 SAM7S321/32

The Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S321/32 contains 8 lock regions and each lock region contains 32 pages of 128 bytes. Each lock region has a size of 4 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC_FMR register.

Figure 9-1. System Controller Block Diagram (SAM7S512/256/128/64/321/161)

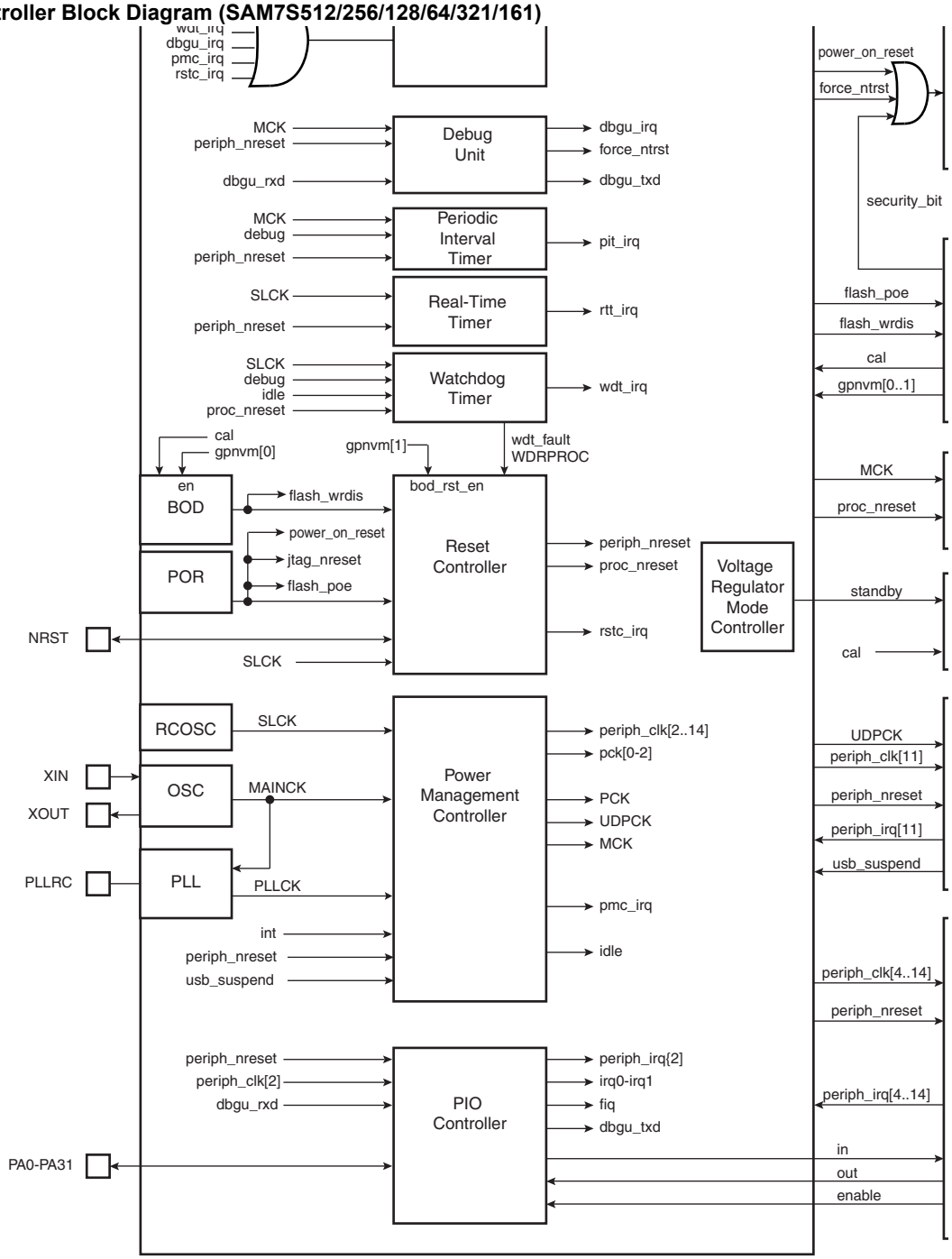
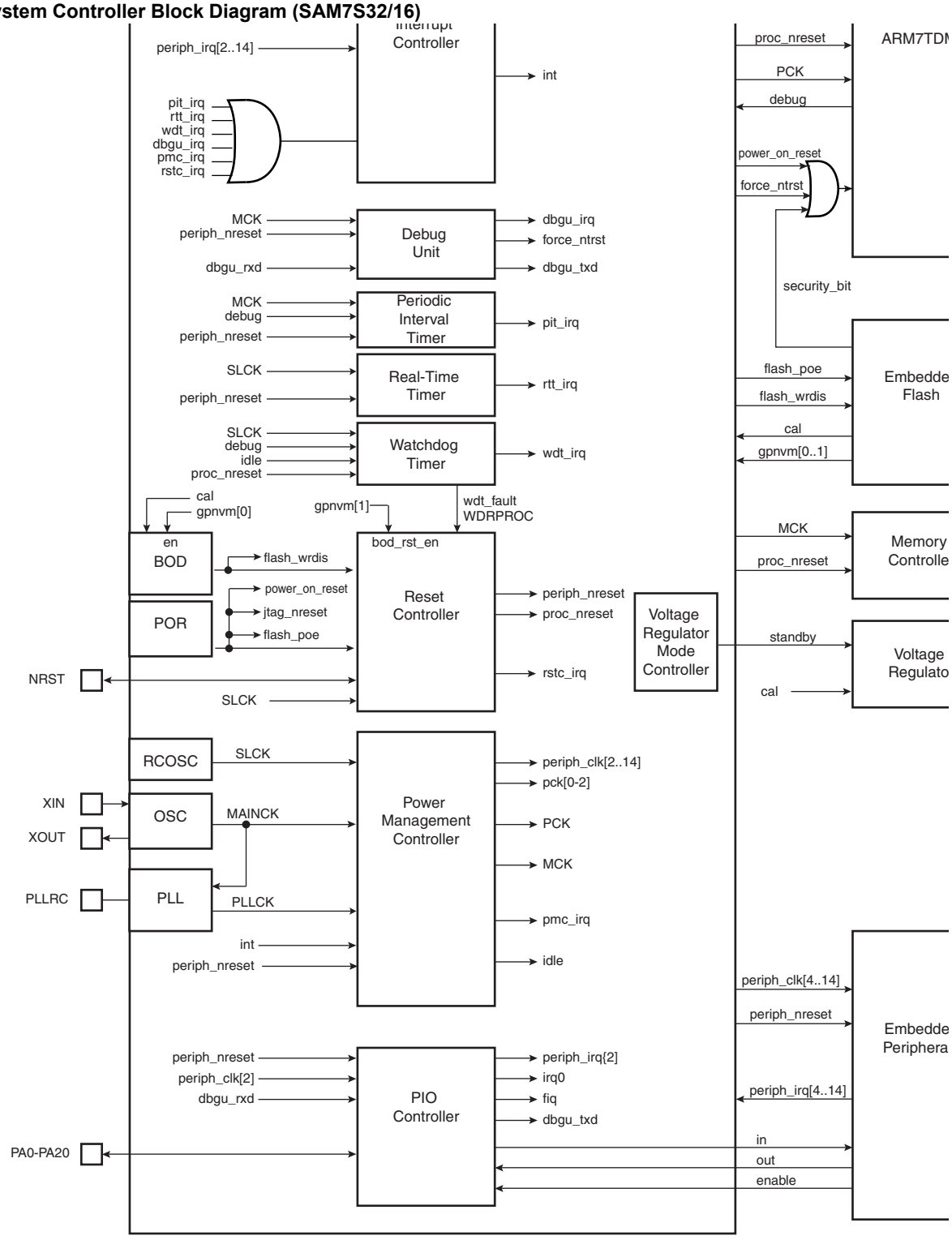


Figure 9-2. System Controller Block Diagram (SAM7S32/16)



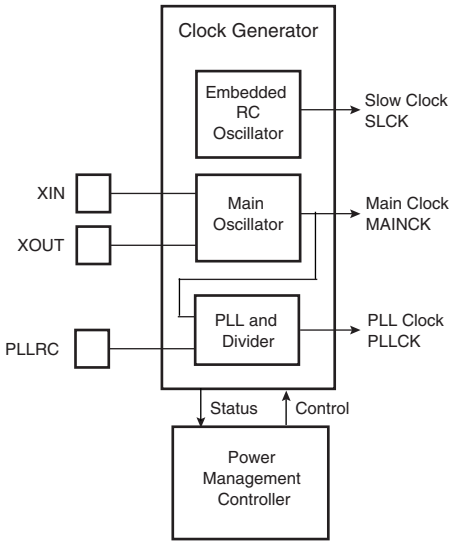
9.2 Clock Generator

The Clock Generator embeds one low-power RC Oscillator, one Main Oscillator and one PLL with the following characteristics:

- RC Oscillator ranges between 22 kHz and 42 kHz
- Main Oscillator frequency ranges between 3 and 20 MHz
- Main Oscillator can be bypassed
- PLL output ranges between 80 and 220 MHz

It provides SLCK, MAINCK and PLLCK.

Figure 9-3. Clock Generator Block Diagram



9.3 Power Management Controller

The Power Management Controller uses the Clock Generator outputs to provide:

- the Processor Clock PCK
- the Master Clock MCK
- the USB Clock UDPCK (not present on SAM7S32/16)
- all the peripheral clocks, independently controllable
- three programmable clock outputs

The Master Clock (MCK) is programmable from a few hundred Hz to the maximum operating frequency of the device.

The Processor Clock (PCK) switches off when entering processor idle mode, thus allowing reduced power consumption while waiting for an interrupt.

- One set of Chip ID Registers
- One Interface providing ICE Access Prevention

- Two-pin UART
  - Implemented features are compatible with the USART
  - Programmable Baud Rate Generator
  - Parity, Framing and Overrun Error
  - Automatic Echo, Local Loopback and Remote Loopback Channel Modes
- Debug Communication Channel Support
  - Offers visibility of COMMRX and COMMTX signals from the ARM Processor
- Chip ID Registers
  - Identification of the device revision, sizes of the embedded memories, set of peripherals
  - Chip ID is 0x270B0A40 for AT91SAM7S512 Rev A
  - Chip ID is 0x270B0A4F for AT91SAM7S512 Rev B
  - Chip ID is 0x270D0940 for AT91SAM7S256 Rev A
  - Chip ID is 0x270B0941 for AT91SAM7S256 Rev B
  - Chip ID is 0x270B0942 for AT91SAM7S256 Rev C
  - Chip ID is TBD for AT91SAM7S256 Rev D
  - Chip ID is 0x270C0740 for AT91SAM7S128 Rev A
  - Chip ID is 0x270A0741 for AT91SAM7S128 Rev B
  - Chip ID is 0x270A0742 for AT91SAM7S128 Rev C
  - Chip ID is TBD for AT91SAM7S128 Rev D
  - Chip ID is 0x27090540 for AT91SAM7S64 Rev A
  - Chip ID is 0x27090543 for AT91SAM7S64 Rev B
  - Chip ID is 0x27090544 for AT91SAM7S64 Rev C
  - Chip ID is 0x27080342 for AT91SAM7S321 Rev A
  - Chip ID is 0x27080340 for AT91SAM7S32 Rev A
  - Chip ID is 0x27080341 for AT91SAM7S32 Rev B
  - Chip ID is 0x27050241 for AT9SAM7S161 Rev A
  - Chip ID is 0x27050240 for AT91SAM7S16 Rev A

Note: Refer to the errata section of the datasheet for updates on chip ID.

9.6 Periodic Interval Timer

- 20-bit programmable counter plus 12-bit interval counter

9.7 Watchdog Timer

- 12-bit key-protected Programmable Counter running on prescaled SCLK
- Provides reset or interrupt signals to the system
- Counter may be stopped while the processor is in debug state or in idle mode

9.8 Real-time Timer

- 32-bit free-running counter with alarm running on prescaled SCLK
- Programmable 16-bit prescaler for SLCK accuracy compensation

9.9 PIO Controller

- One PIO Controller, controlling 32 I/O lines (21 for SAM7S32/16)
- Fully programmable through set/clear registers
- Multiplexing of two peripheral functions per I/O line
- For each I/O line (whether assigned to a peripheral or used as general-purpose I/O)
  - Input change interrupt
  - Half a clock period glitch filter
  - Multi-drive option enables driving in open drain
  - Programmable pull-up on each I/O line
  - Pin data status register, supplies visibility of the level on the pin at any time
- Synchronous output, provides Set and Clear of several I/O lines in a single write

9.10 Voltage Regulator Controller

The aim of this controller is to select the Power Mode of the Voltage Regulator between Normal Mode (bit 0 is cleared) or Standby Mode (bit 0 is set).

10.4 PIO Controller A Multiplexing

Table 10-3. Multiplexing on PIO Controller A (SAM7S512/256/128/64/321/161)

PA0	PWM0	TIOA0	High-Drive		
PA1	PWM1	TIOB0	High-Drive		
PA2	PWM2	SCK0	High-Drive		
PA3	TWD	NPCS3	High-Drive		
PA4	TWCK	TCLK0			
PA5	RXD0	NPCS3			
PA6	TXD0	PCK0			
PA7	RTS0	PWM3			
PA8	CTS0	ADTRG			
PA9	DRXD	NPCS1			
PA10	DTXD	NPCS2			
PA11	NPCS0	PWM0			
PA12	MISO	PWM1			
PA13	MOSI	PWM2			
PA14	SPCK	PWM3			
PA15	TF	TIOA1			
PA16	TK	TIOB1			
PA17	TD	PCK1	AD0		
PA18	RD	PCK2	AD1		
PA19	RK	FIQ	AD2		
PA20	RF	IRQ0	AD3		
PA21	RXD1	PCK1			
PA22	TXD1	NPCS3			
PA23	SCK1	PWM0			
PA24	RTS1	PWM1			
PA25	CTS1	PWM2			
PA26	DCD1	TIOA2			
PA27	DTR1	TIOB2			
PA28	DSR1	TCLK1			
PA29	RI1	TCLK2			
PA30	IRQ1	NPCS2			
PA31	NPCS1	PCK2			

11. Package Drawings

The SAM7S series devices are available in LQFP and QFN package types.

11.1 LQFP Packages

Figure 11-1. 48-and 64-lead LQFP Package Drawing

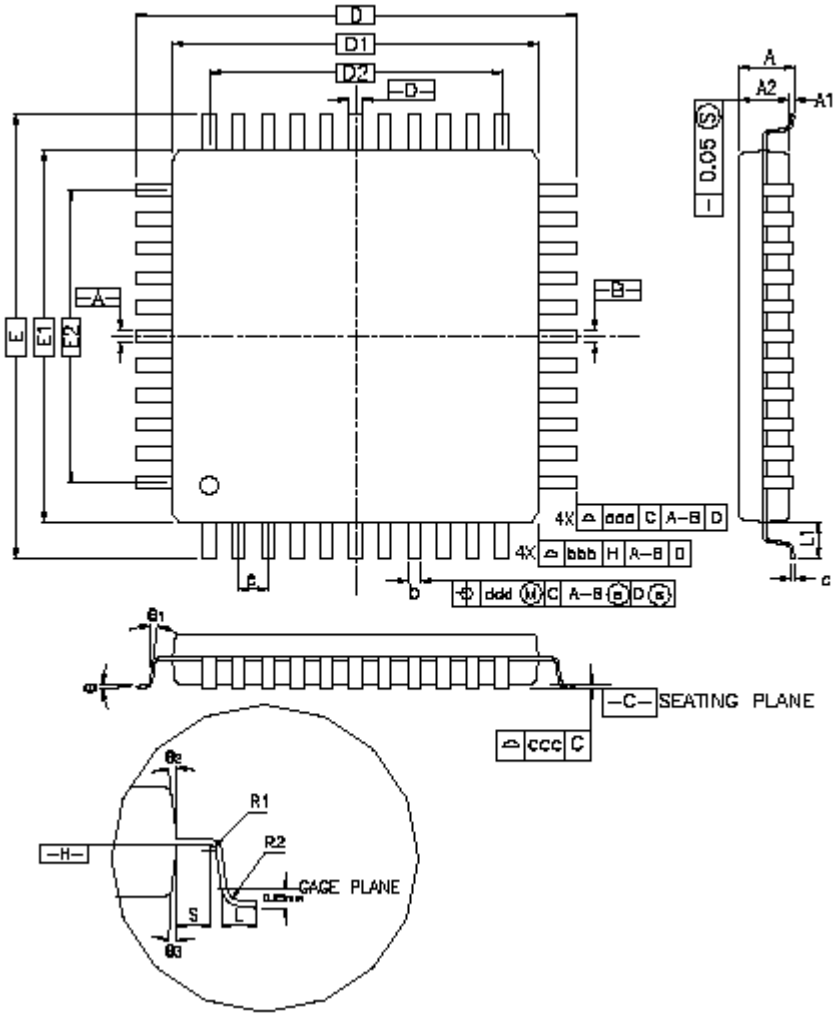


Table 11-1. 48-lead LQFP Package Dimensions (in mm)

Symbol						
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	9.00 BSC			0.354 BSC		
D1	7.00 BSC			0.276 BSC		
E	9.00 BSC			0.354 BSC		
E1	7.00 BSC			0.276 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	5.50			0.217		
E2	5.50			0.217		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Table 11-2. 64-lead LQFP Package Dimensions (in mm)

Symbol						
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.285		
E2	7.50			0.285		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Revision History

6175AS	First issue - Unqualified on Intranet Corresponds to 6175A full datasheet approval loop. Qualified on Intranet.	
6175BS	Section 8. “Memories” on page 18 updated: 2 ms => 3 ms, 10 ms => 15 ms, 4 ms => 6 ms	CSR05-529
6175CS	Section 12. ”SAM7S Ordering Information” AT91SAM7S321 changed in Table 12-1 on page 47	#2342
6175DS	“Features” , Table 1-1, “Configuration Summary,” on page 3, Section 4. ”Package and Pinout” Section 12. ”SAM7S Ordering Information” QFN package information added	#2444
6175ES	Section 10.11 on page 39 USB Device port, Ping-pong Mode includes Isochronous endpoints. “Features” on page 1, and global: AT91SAM7S512 added to series. Reference to Manchester Encoder removed from USART. Section 8. ”Memories” Reformatted Memories, Consolidated Memory Mapping in Figure 8-1 on page 20 Section 10. ”Peripherals” Reordered sub sections. Section 11. ”Package Drawings” QFN, LQFP package drawings added. “ice_nreset” signals changed to” power_on_reset” in System Controller block diagrams, Figure 9-1 on page 26 and Figure 9-2 on page 27. Section 4. ”Package and Pinout” LQFP and QFN Package Outlines replace Mechanical Overview. Section 10.1 ”User Interface”, User peripherals are mapped between 0xF000 0000 and 0xFFFF EFFF. SYSIRQ changed to SYSC in “Peripheral Identifiers” Table 10-1 and Table 10-2	specs #2748 #2832 (DBGU IP) rfo review
6175FS	AT91SAM7S161 and AT91SAM7S16 added to product family **Features:** Timer Counter, on page 2 product specific information rewritten, Table 1-1, “Configuration Summary,” on page 3, footnote explains TC on AT91SAM7S32/16 has only two channels accessible via PIO, and in Section 10.9 ”Timer Counter”, precisions added to “compare and capture” output/input. Section 10.6 ”Two-wire Interface”, updated reference to I^2C compatibility, internal address registers, slave addressing, Modes for AT91SAM7S161/16 “One Two-wire Interface (TWI)” on page 2, updated in Features Section 10.12 ”Analog-to-digital Converter”, updated Successive Approximation Register ADC and the INL, DNL ± values of LSB. Section 8.8.3 ”Lock Regions”, locked-region’s erase or program command updated Section 9.5 ”Debug Unit”, Chip ID updated. Section 6. ”I/O Lines Considerations”, JTAG Port Pin, Test Pin, Erase Pin, updated.	BDs 4208 rfo review 4325 5063

6175GS	“Features” ,“Debug Unit (DBGU)” updated with “Mode for General Purpose 2-wire UART Serial Communication” Section 7.4 ”Peripheral DMA Controller”, added list of PDC priorities. Section 9. ”System Controller”, Figure 9-1 and Figure 9-2 RTT is reset by “power_on_reset”. Section 9.1.1 ”Brownout Detector and Power-on Reset”, fourth paragraph reduced. Section 9.5 ”Debug Unit”, the list; Section I ”Chip ID Registers”, chip IDs updated, added SAM7S32 Rev B and SAM7S64 Rev B to the list. Section 12. ”SAM7S Ordering Information”, Updated product ordering information by MRL A and MRL B versions.	5846 5913 5224 5685 rfo
6175HS	Section 6.2 ”Test Pin”, added to SAM-BA Boot recovery procedure, a power cycle of the board is mandatory. Section 8.10 ”SAM-BA Boot Assistant”, added to SAM-BA Boot recovery procedure, a power cycle of the board is mandatory.	6068
6175IS	Section 9.5 ”Debug Unit”, Chip ID Registers list updated. MRL C column added to Table 12-1, “SAM7S Series Ordering Information”.	7185
6175JS	Product Series Naming Convention Except for part ordering and library references, AT91 prefix dropped from most nomenclature. AT91SAM7S becomes SAM7S. Debug Unit: “Chip ID Registers” on page 31, Chip ID is 0x270B0A4F for AT91SAM7S512 Rev B	rfo 7945
6175KS	Section 9.5 ”Debug Unit”, Chip ID Registers list updated. Added Chip ID for SAM7S128 Rev D and SAM7S256 Rev D Table 12-1, “SAM7S Series Ordering Information”.Added SAM7S128 Rev D and SAM7S256 Rev D	8380/8467